The International Conference on Software Engineering brings together researchers and practitioners from around the world for a week of presentations and discussion around leading innovations, trends, outcomes, and experiences in software engineering. A quarter-century after the first ICSE in Austin, ICSE 2016 continues the tradition of the past, fostering transformative advances in research and practice through free exchange of ideas and collaboration.

We invite you to help shape ICSE 2016 through submission to one or more of our many tracks for professional engagement. In particular, organizers welcome submission of technical research papers; proposals for technical briefings in emerging areas; practice and experience papers; education papers; vision papers: predicting novel future challenges for 2025 and beyond, or proposing solutions to such challenges; proposals for topical workshops; doctoral student research prospectuses, posters, and formal demonstrations.

The technical research track invites high quality submissions of papers, describing original and unpublished results of conceptual, constructive, empirical, experimental, or theoretical work, in all areas of software engineering. See the conference website for guidelines in all submission categories.

ICSE 2016 Call for Submissions

Important Dates

Aug 28, 2015  Technical research papers
Oct 10, 2015  Workshop proposals
Oct 23, 2015  Software Engineering in Practice  •  Software Engineering Education and Training  •  Software Engineering in Society  •  Visions of 2025 and Beyond
Nov 20, 2015  Doctoral Symposium  •  ACM Student Research Competition  •  Formal Demonstrations  •  Technical briefing proposals
Jan 13, 2016  Posters

Mark your calendars and join us to make the 38th ICSE one for the record books. As the saying goes, “Everything is bigger in Texas!”

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Proceedings

Accepted papers will be published in the ICSE 2016 conference or conference companion proceedings and in the digital libraries of ACM and IEEE Computer Society. The official publication date is the date the proceedings are made available in the ACM Digital Library. This date may be up to two weeks prior to the first day of ICSE 2016. The official publication date affects the deadline for any patent filings related to the published work.

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“Austin is the Texas State Capital

Austin has become a hub for technology, entrepreneurship, music, and recreation. ICSE 2016 will be in the Austin Arboretum Area—dubbed “New Austin”—and at the peak of the Texas wildflower season. It will be an ideal setting for flourishing new ideas in software engineering.

While you are here, check out some of the sights and sounds of Austin. Whether you like to visit museums, view historical sights, or take tours, there is something for everyone. For more information on the area, visit: [http://www.austintexas.org/visit/discover/](http://www.austintexas.org/visit/discover/)